



10N65 10N65F 10N65D 10N65E 650V N-Channel Power MOSFET

FEATURES

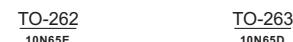
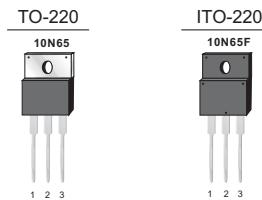
- $R_{DS(ON)} < 0.85 \Omega$ @ $V_{GS} = 10V$
- Fast switching capability
- Low Gate Charge
- Lead free in compliance with EU RoHS directive.

MECHANICAL DATA

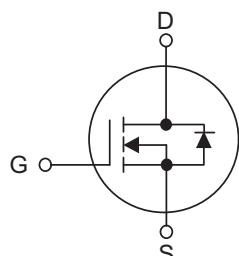
- Case: TO-220, ITO-220, TO-262, TO-263 Package

PRODUCT SUMMARY

$V_{DS}(V)$	$R_{DS(ON)}(\Omega)$	$I_D(A)$
650	0.75 @ $V_{GS} = 10V$	10



Block Diagram



Pin Definition:
1. Gate
2. Drain
3. Source

ABSOLUTE MAXIMUM RATINGS ($T_C = 25^\circ C$, unless otherwise specified)

PARAMETER	SYMBOL	RATINGS	UNIT
Drain-Source Voltage	V_{DS}	650	V
Gate-Source Voltage	V_{GS}	± 30	V
Continuous Drain Current	I_D	10	A
Pulsed Drain Current (Note 1)	I_{DM}	40	A
Avalanche Energy (Note 5)	E_{AS}	500	mJ
Power Dissipation	TO-220/TO-263/TO-262	P_D	W
		130	
	ITO-220	40	
Junction Temperature	T_J	+150	C
Storage Temperature	T_{STG}	-55 ~ +150	C

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THERMAL DATA

PARAMETER		SYMBOL	RATING	UNIT
Junction to Ambient	TO-220/TO-251/TO-252 TO-262/TO-263 ITO-220	θ_{JA}	62.5	C/W
Junction to Case	TO-220/TO-263/TO-262	θ_{JC}	0.96	C/W
	ITO-220		3.13	

ELECTRICAL CHARACTERISTICS (T_C=25 C, unless otherwise specified)

PARAMETER	SYMBOL	TEST CONDITIONS	MIN	TYP	MAX	UNIT
OFF CHARACTERISTICS						
Drain-Source Breakdown Voltage	V_{DSS}	$V_{GS}=0V, I_D=250\mu A$	650			V
Drain-Source Leakage Current	I_{DS}	$V_{DS}=650V, V_{GS}=0V$		1		μA
Gate- Source Leakage Current	Forward	$V_{GS}=30V, V_{DS}=0V$		100		nA
	Reverse	$V_{GS}=-30V, V_{DS}=0V$		-100		nA
ON CHARACTERISTICS(Note 3)						
Gate Threshold Voltage	$V_{GS(TH)}$	$V_{DS}=V_{GS}, I_D=250\mu A$	2.0		4.0	V
Static Drain-Source On-State Resistance	$R_{DS(ON)}$	$V_{GS}=10V, I_D=5A$		0.75	0.85	Ω
DYNAMIC CHARACTERISTICS(Note 4)						
Input Capacitance	C_{ISS}	$V_{DS}=25V, V_{GS}=0V, f=1MHz$		1642		pF
Output Capacitance	C_{OSS}			128		pF
Reverse Transfer Capacitance	C_{RSS}			7		pF
SWITCHING CHARACTERISTICS (Note 4)						
Turn-On Delay Time	$t_{D(ON)}$	$V_{DD}=325V, I_D=10A, R_G=10\Omega$		27		ns
Turn-On Rise Time	t_R			22		ns
Turn-Off Delay Time	$t_{D(OFF)}$			53		ns
Turn-Off Fall Time	t_F			24		ns
Total Gate Charge	Q_G	$V_{DS}=520V, I_D=10A, V_{GS}=10V$		32		nC
Gate-Source Charge	Q_{GS}			8		nC
Gate-Drain Charge	Q_{GD}			12		nC
DRAIN-SOURCE DIODE CHARACTERISTICS AND MAXIMUM RATINGS						
Drain-Source Diode Forward Voltage	V_{SD}	$V_{GS}=0V, I_S=10A$			1.5	V
Maximum Continuous Drain-Source Diode Forward Current (Note 2)	I_S				10	A
Reverse Recovery Current	I_{RRM}			12.2		A
Reverse Recovery Time	t_{rr}	$V_{GS}=0V, I_S=10A$ $dI_F/dt=100A/\mu s$ (Note 1)		528		ns
Reverse Recovery Charge	Q_{RR}			3220		nC

Note:1. Repetitive Rating : Pulse width limited by maximum junction temperature

2. Surface mounted on FR4 Board ,t≤10sec
3. Pulse Test: Pulse width ≤300μS, Duty cycle≤2%.
4. Guaranteed by design,not subject to production.
5. L=10mH, $I_D=10A, V_{DD}=50V, V_{GATE}=650V$,Starting $T_J=25 C$

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Typical characteristics Diagrams

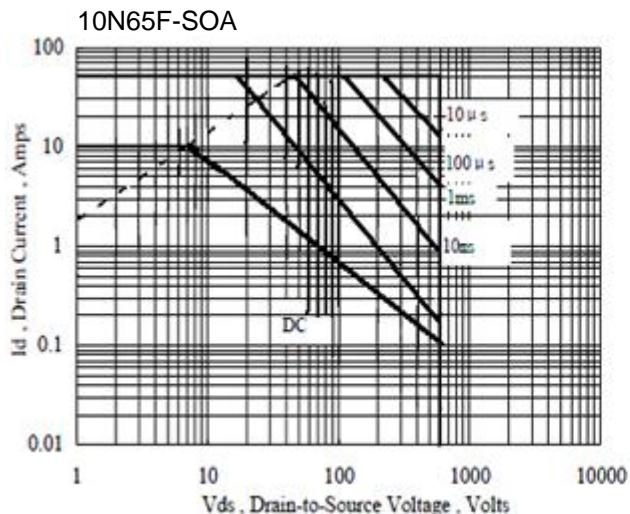


Figure 1 Maximum Forward Bias Safe Operating Area

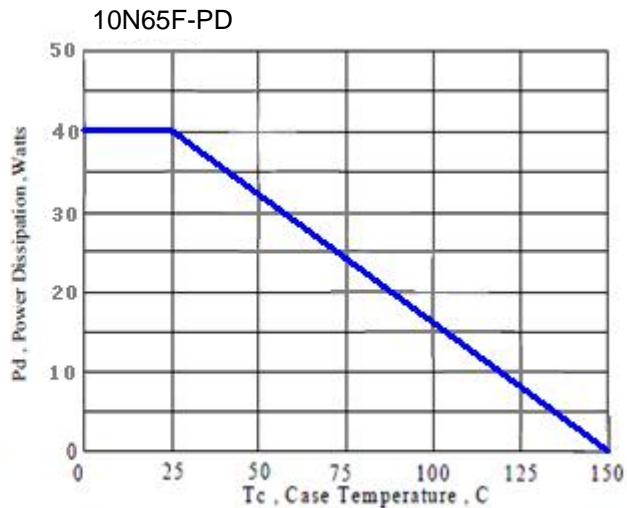


Figure 2 Maximum Power Dissipation vs Case Temperature

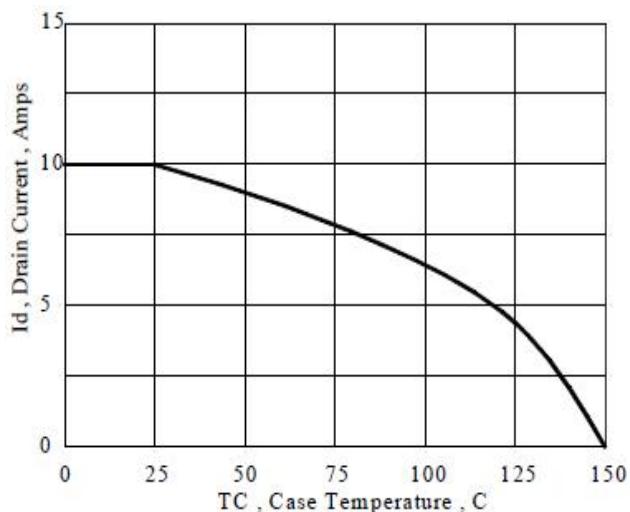


Figure 3 Maximum Continuous Drain Current vs Case Temperature

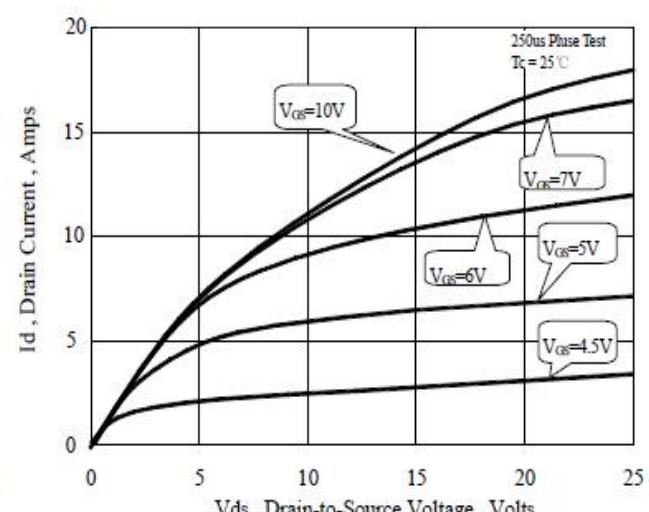


Figure 4 Typical Output Characteristics

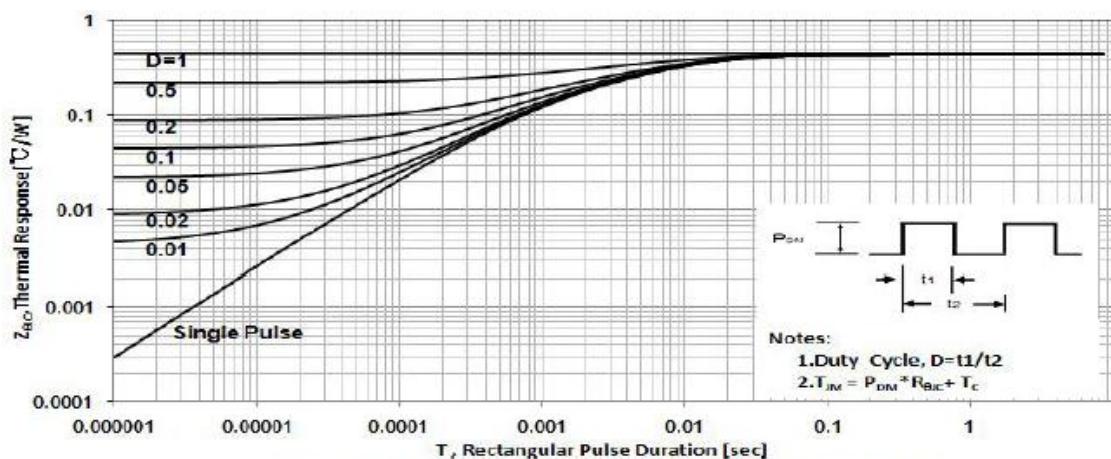


Figure 5 Maximum Effective Thermal Impedance . Junction to Case

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Typical characteristics Diagrams

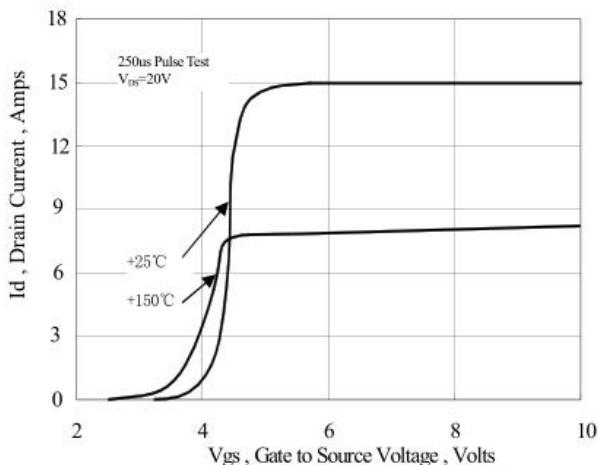


Figure 6 Typical Transfer Characteristics

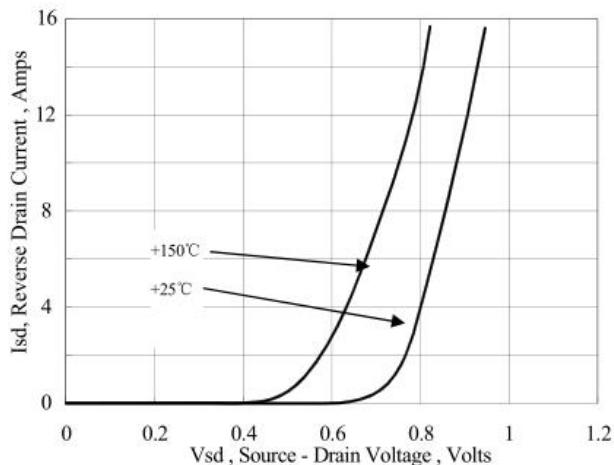


Figure 7 Typical Body Diode Transfer Characteristics

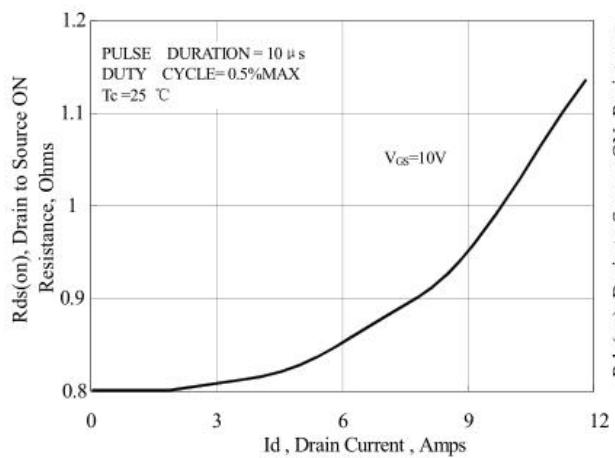


Figure 8 Typical Drain to Source ON Resistance vs Drain Current

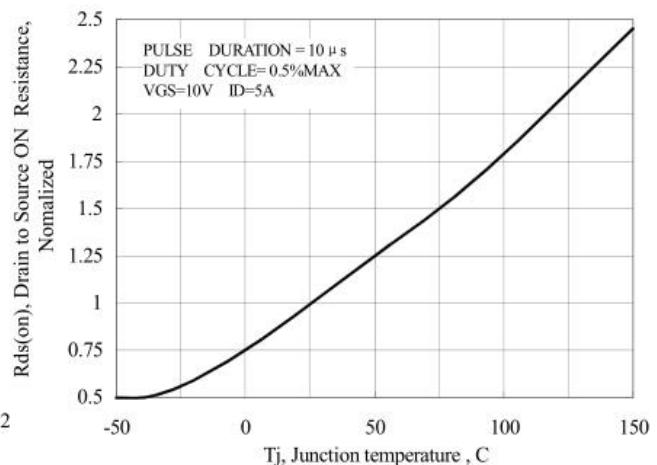


Figure 9 Typical Drian to Source on Resistance vs Junction Temperature

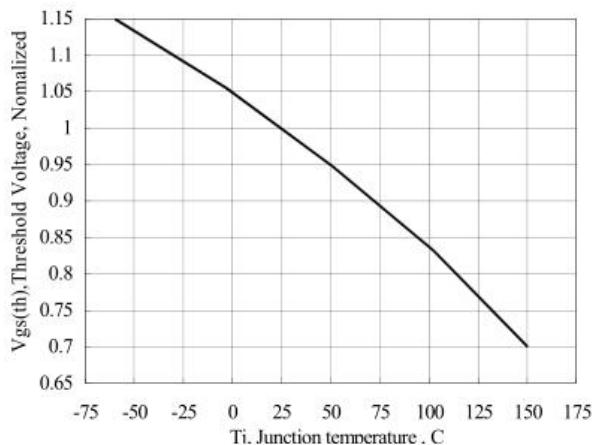


Figure 10 Typical Theshold Voltage vs Junction Temperature

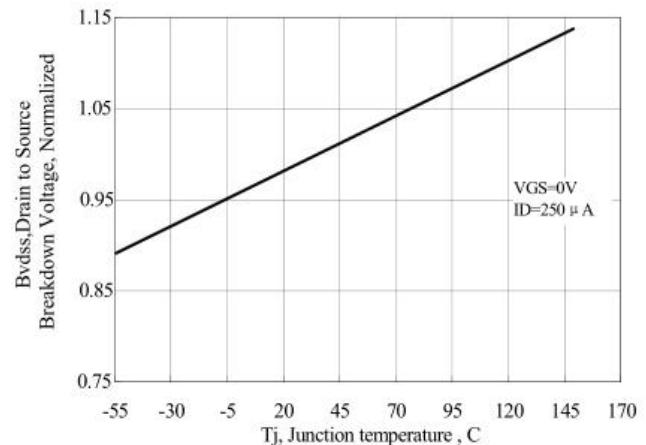


Figure 11 Typical Breakdown Voltage vs Junction Temperature

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Typical characteristics Diagrams

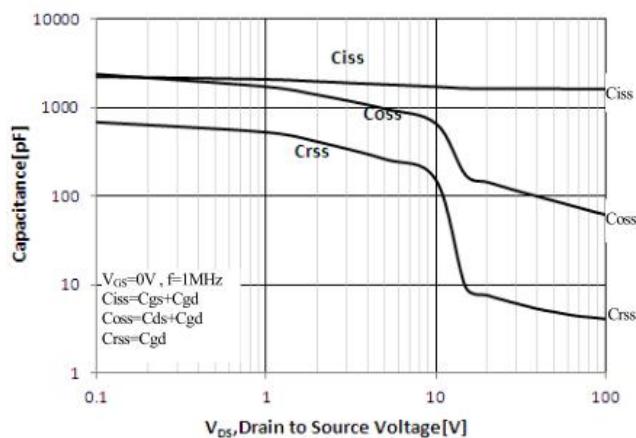


Figure 12 Typical Capacitance vs Drain to Source Voltage

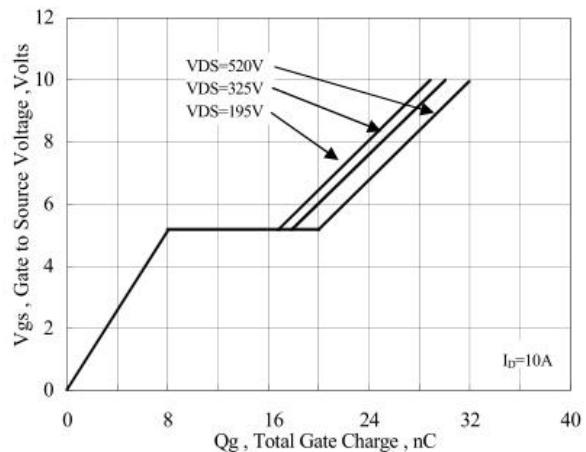


Figure 13 Typical Gate Charge vs Gate to Source Voltage

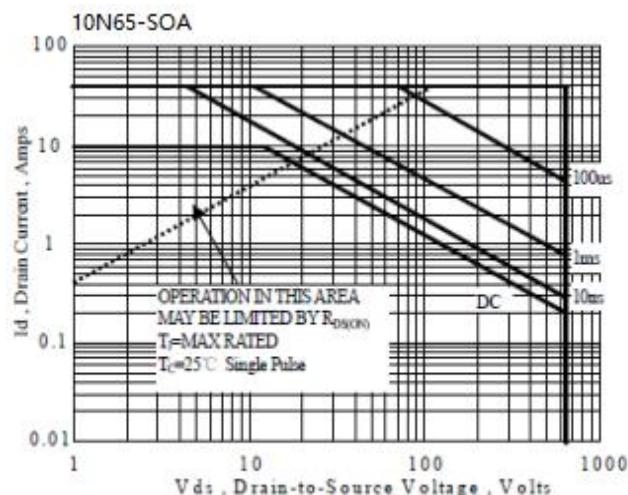


Figure 14 Maximum Forward Bias Safe Operating Area

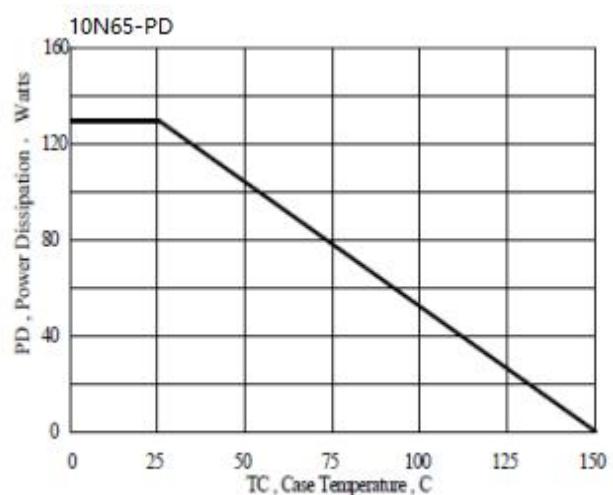


Figure 15 Maximum Power Dissipation vs Case Temperature

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TYPICAL TEST CIRCUIT

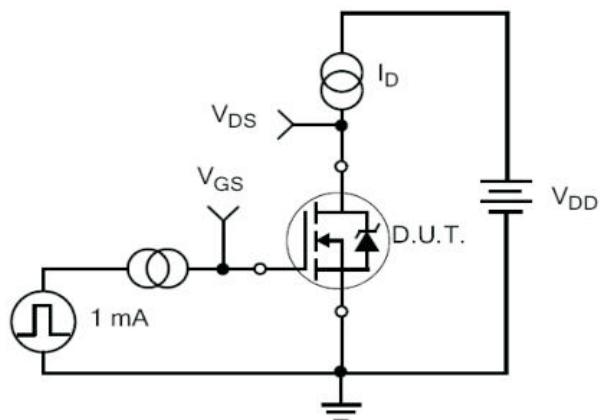


Figure 17. Gate Charge Test Circuit

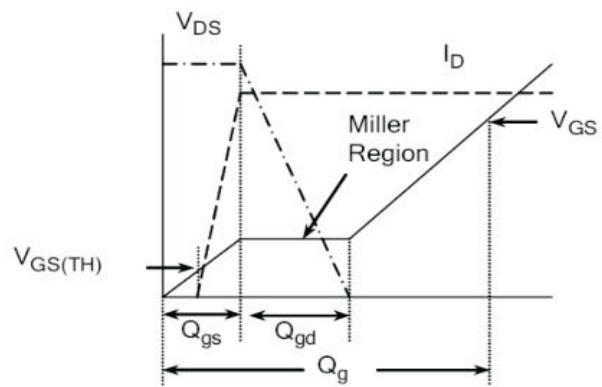


Figure 18. Gate Charge Waveform

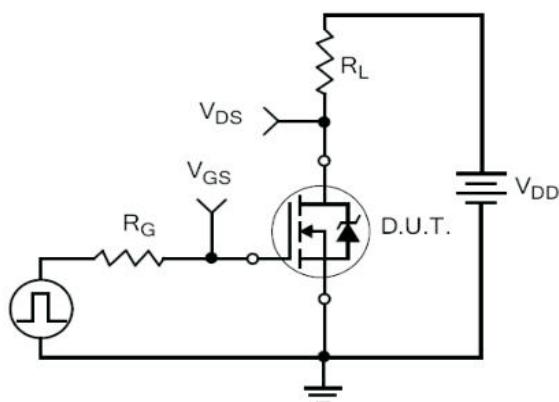


Figure 19. Resistive Switching Test Circuit

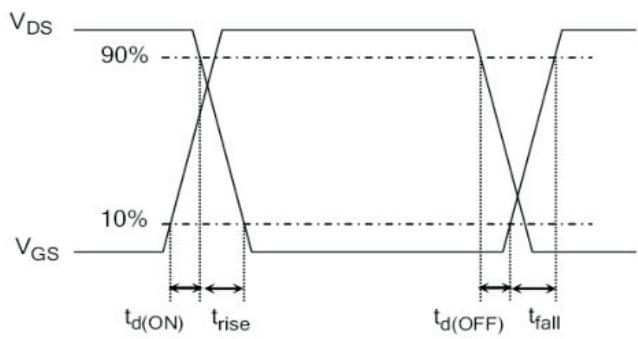


Figure 20. Resistive Switching Waveforms

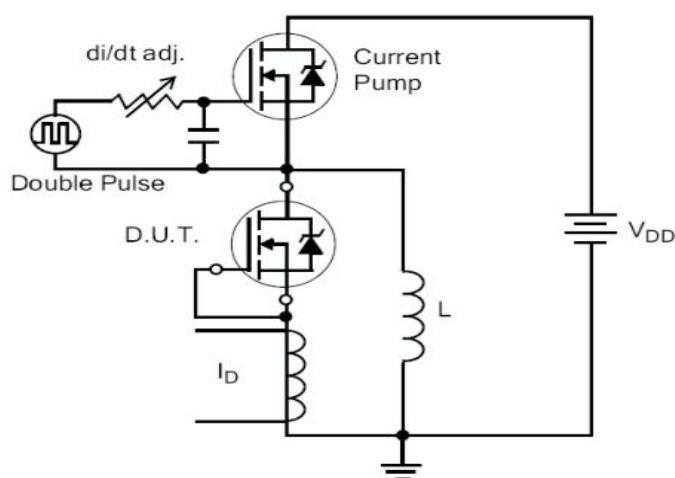


Figure 21. Diode Reverse Recovery Test Circuit

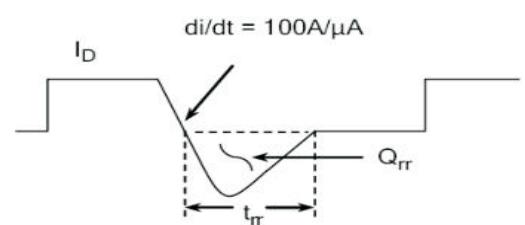


Figure 22. Diode Reverse Recovery Waveform

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TYPICAL TEST CIRCUIT AND WAVEFORM(CONTINUES)

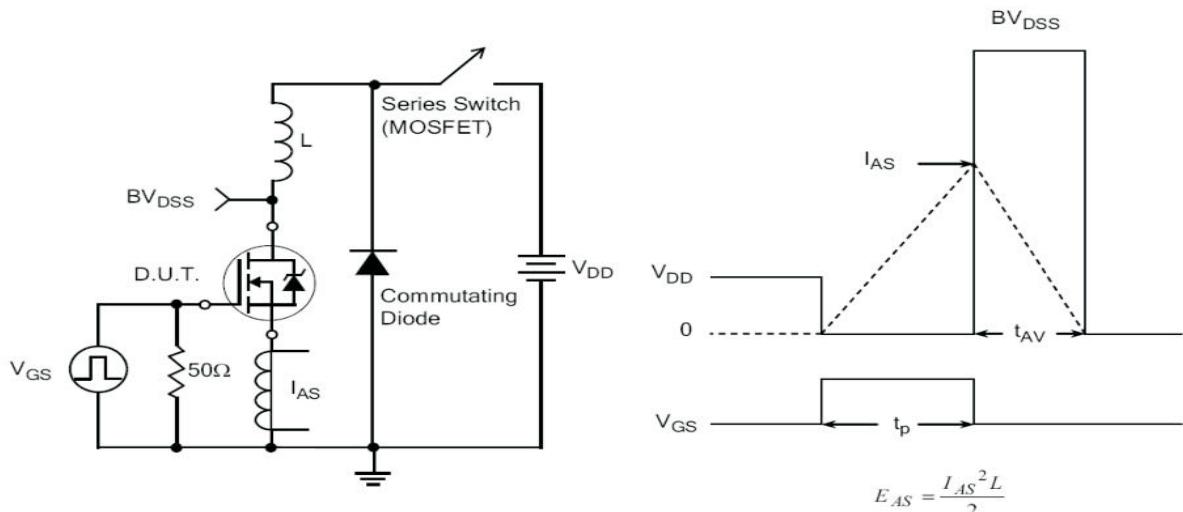
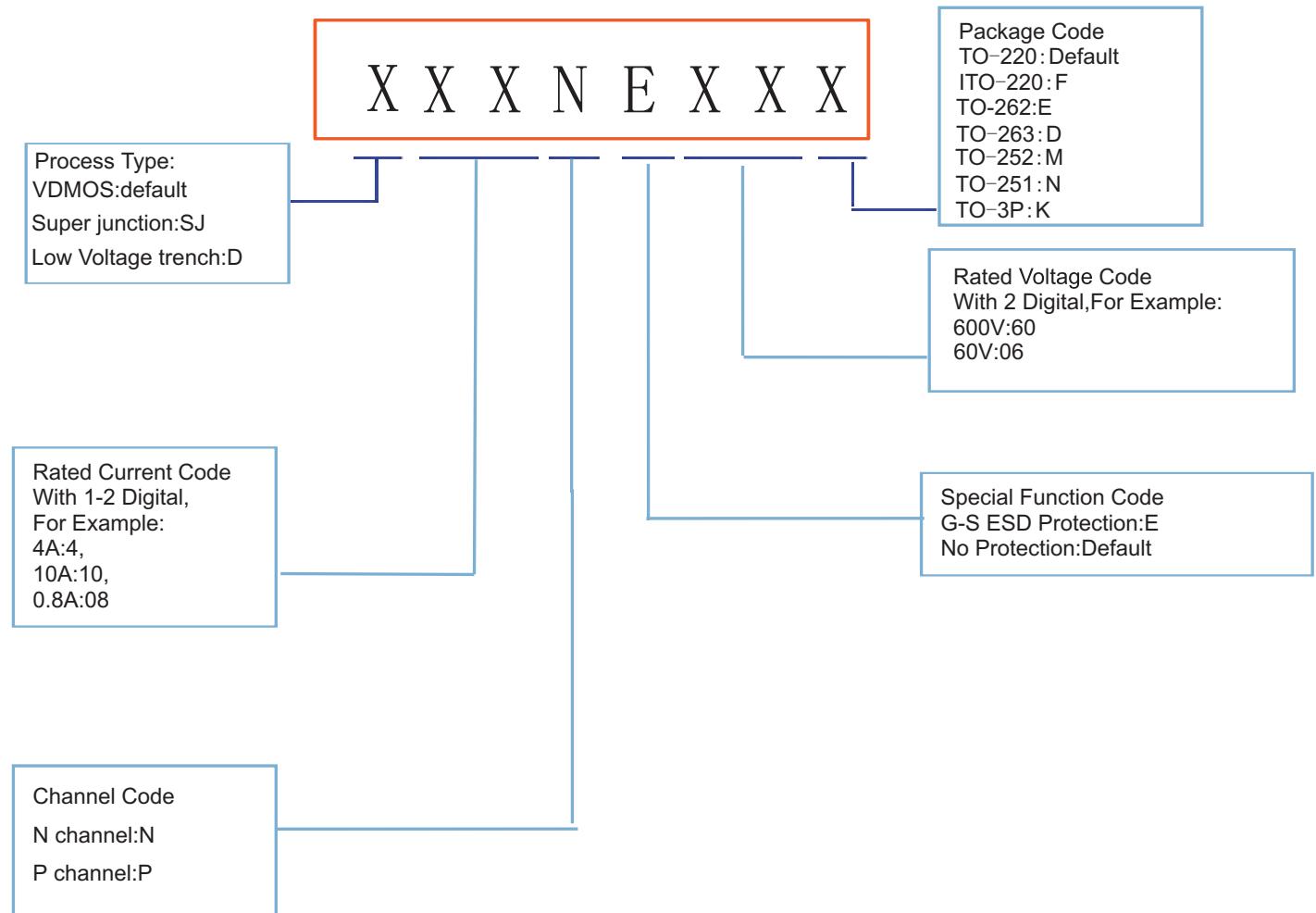


Figure 23. Unclamped Inductive Switching Test Circuit

Figure 24. Unclamped Inductive Switching Waveforms

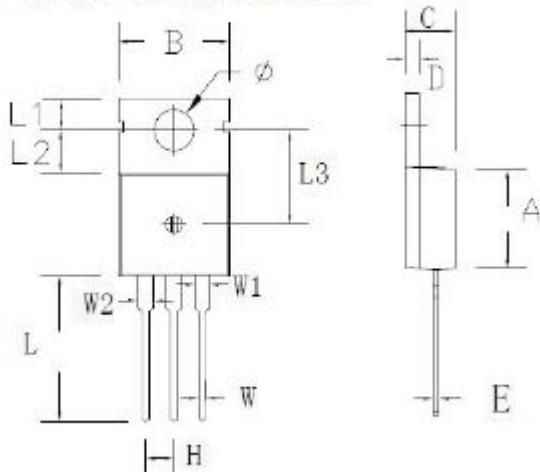
Product Names Rules



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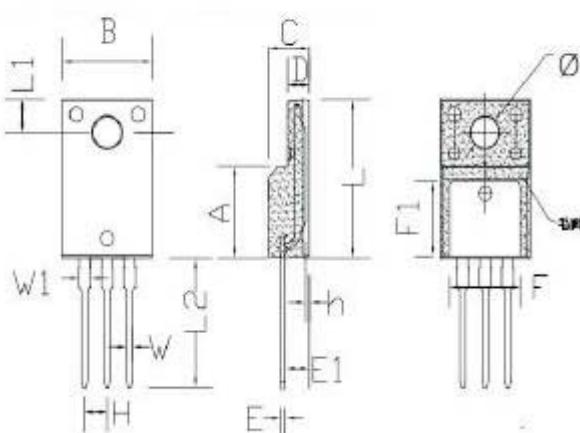
Dimensions

TO-220 PACKAGE OUTLINE DIMENSIONS



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	min.	max.	min.	max.
A	8.80	9.30	0.346	0.366
B	9.70	10.30	0.382	0.406
C	4.25	4.75	0.167	0.187
D	1.20	1.45	0.047	0.057
E	0.40	0.60	0.016	0.024
H	2.54 TYP		0.100 TYP	
W	0.60	0.95	0.024	0.037
W1	1.05	1.45	0.041	0.057
W2	1.20	1.60	0.047	0.063
L	12.60	13.40	0.496	0.528
L1	2.45	2.95	0.096	0.116
L2	3.45	3.95	0.136	0.156
L3	8.15	8.65	0.321	0.341
Φ	3.50	3.90	0.138	0.154

ITO-220 PACKAGE OUTLINE DIMENSIONS

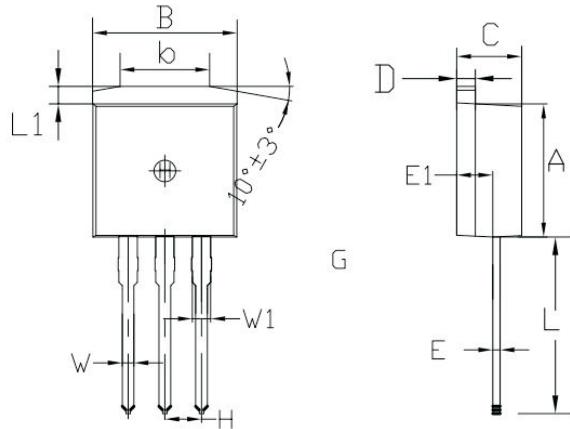


Symbol	Dimensions In Millimeters		Dimensions In Inches	
	min.	max.	min.	max.
A	8.80	9.30	0.346	0.366
B	10.00	10.50	0.394	0.413
C	4.30	4.90	0.169	0.193
D	2.30	2.70	0.091	0.106
L	15.55	16.15	0.612	0.636
h	0.40	0.60	0.016	0.024
L1	3.15	3.55	0.124	0.140
L2	12.65	13.35	0.498	0.526
W	0.70	0.90	0.028	0.035
W1	1.15	1.55	0.045	0.061
H	2.54 TYP		0.100 TYP	
E	0.48	0.53	0.019	0.021
Φ	2.90	3.40	0.114	0.134
E1	2.40	2.90	0.094	0.114
F	7.75	8.25	0.305	0.325
F1	7.35	7.85	0.289	0.309

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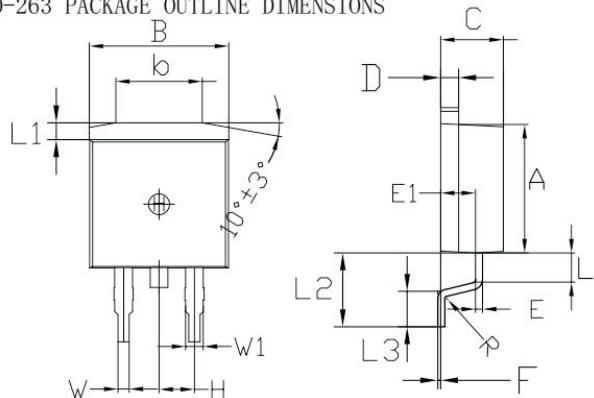
Dimensions

TO-262 PACKAGE OUTLINE DIMENSIONS



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	min.	max.	min.	max.
A	8.80	9.30	0.346	0.366
B	9.70	10.30	0.382	0.406
C	4.25	4.75	0.167	0.187
D	1.20	1.45	0.047	0.057
E	0.40	0.60	0.016	0.024
L	12.25	13.75	0.482	0.541
L1	1.15	1.45	0.045	0.057
E1	2.4	2.6	0.0945	0.1024
W	0.80	0.82	0.0315	0.034
W1	1.20	1.30	0.047	0.051
H	2.54 TYP		0.200 TYP	
b	5.50	6.50	0.216	0.256

TO-263 PACKAGE OUTLINE DIMENSIONS



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	min.	max.	min.	max.
A	8.80	9.30	0.346	0.366
B	9.70	10.30	0.382	0.406
C	4.25	4.75	0.167	0.187
D	1.20	1.45	0.047	0.057
E	0.40	0.60	0.016	0.024
L	1.90	2.30	0.075	0.091
L1	1.15	1.45	0.045	0.057
R	0.24	0.26	0.0095	0.0102
W	0.80	0.82	0.0315	0.0323
W1	1.20	1.30	0.047	0.051
H	2.54 TYP		0.200 TYP	
b	5.50	6.50	0.216	0.256
E1	2.4	2.6	0.0946	0.1024
L2	5.20	5.80	0.205	0.228
L3	2.20	3.20	0.087	0.126
F	0.03	0.23	0.0012	0.0091